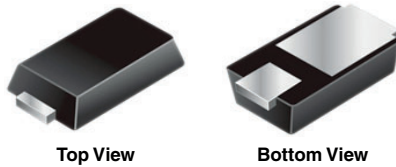


Surface-Mount Ultrafast Rectifiers

eSMP® Series



Top View

Bottom View

MicroSMP (DO-219AD)

Anode Cathode

FEATURES

- Very low profile - typical height of 0.65 mm
- Ideal for automated placement
- Oxide planar chip junction
- Low forward voltage drop, low power losses
- Ultrafast recovery times for high frequency
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- AEC-Q101 qualified
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

 AUTOMOTIVE
GRADE
Available

RoHS
COMPLIANT
HALOGEN
FREE

LINKS TO ADDITIONAL RESOURCES



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	1.0 A
V_{RRM}	100 V, 150 V
I_{FSM}	10 A
t_{rr}	25 ns
V_F at $I_F = 1.0$ A	0.82 V
I_R	1 μ A
T_J max.	175 °C
Package	MicroSMP (DO-219AD)
Circuit configuration	Single

TYPICAL APPLICATIONS

For use in secondary rectification and freewheeling for ultrafast switching speeds AC/AC and DC/DC converters.

MECHANICAL DATA

Case: MicroSMP (DO-219AD)

Molding compound meets UL 94 V-0 flammability rating
Base P/N-M3 - halogen-free, RoHS-compliant, and commercial grade

Base P/NHM3 - halogen-free, RoHS-compliant, and automotive grade

Terminals: matte tin plated leads, solderable per J-STD-002 and JESD 22-B102

M3 suffix meets JESD 201 class 2 whisker test, HM3 suffix meets JESD 201 class 2 whisker test

Polarity: color band denotes the cathode end

MAXIMUM RATINGS ($T_A = 25$ °C unless otherwise noted)				
PARAMETER	SYMBOL	MUH1PB	MUH1PC	UNIT
Device marking code		HB	HC	
Maximum repetitive peak reverse voltage	V_{RRM}	100	150	V
Maximum average forward rectified current (fig. 1)	$I_{F(AV)}$	1.0		A
Peak forward surge current 10 ms single half sine-wave superimposed on rated load	I_{FSM}	10		A
Operating junction and storage temperature range	T_J, T_{STG}	-55 to +175		°C



ELECTRICAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)						
PARAMETER	TEST CONDITIONS	SYMBOL	TYP.	MAX.	UNIT	
Maximum instantaneous forward voltage	$I_F = 0.5\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	$V_F^{(1)}$	0.90	-	V
	$I_F = 1.0\text{ A}$			1.0	1.05	
	$I_F = 0.5\text{ A}$	$T_A = 125\text{ }^\circ\text{C}$		0.72	-	
	$I_F = 1.0\text{ A}$			0.82	0.90	
Maximum reverse current	Rated V_R	$T_A = 25\text{ }^\circ\text{C}$	$I_R^{(2)}$	-	1.0	μA
		$T_A = 125\text{ }^\circ\text{C}$		3.0	15	
Maximum reverse recovery time	$I_F = 0.5\text{ A}$, $I_R = 1.0\text{ A}$, $I_{rr} = 0.25\text{ A}$	$T_A = 25\text{ }^\circ\text{C}$	t_{rr}	19	25	ns
Typical reverse recovery time	$I_F = 1.0\text{ A}$, $di/dt = 50\text{ A}/\mu\text{s}$, $V_R = 30\text{ V}$, $I_{rr} = 0.1 I_{RM}$			29	40	
Typical softness factor (t_b/t_a)		$T_A = 125\text{ }^\circ\text{C}$	S	0.5	-	
Typical reverse recovery current	$I_F = 1.0\text{ A}$, $di/dt = 200\text{ A}/\mu\text{s}$, $V_R = 200\text{ V}$		I_{RM}	3.4	4.6	A
Typical stored charge			Q_{rr}	45	-	nC
Typical junction capacitance			4.0 V, 1 MHz	C_J	10	-

Notes(1) Pulse test: 300 μs pulse width, 1 % duty cycle(2) Pulse test: Pulse width $\leq 40\text{ ms}$

THERMAL CHARACTERISTICS ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)				
PARAMETER	SYMBOL	MUH1PB	MUH1PC	UNIT
Typical thermal resistance	$R_{\theta JA}^{(1)}$	166		$^\circ\text{C}/\text{W}$
	$R_{\theta JM}^{(1)}$	40		

Note(1) Free air, mounted on recommended copper pad area. Thermal resistance $R_{\theta JA}$ - from junction to ambient, $R_{\theta JM}$ - and junction to mount

ORDERING INFORMATION (Example)				
PREFERRED P/N	UNIT WEIGHT (g)	PREFERRED PACKAGE CODE	BASE QUANTITY	DELIVERY MODE
MUH1PC-M3/89A	0.006	89A	4500	7" diameter plastic tape and reel
MUH1PCHM3/89A ⁽¹⁾	0.006	89A	4500	7" diameter plastic tape and reel

Note

(1) Automotive grade

RATINGS AND CHARACTERISTICS CURVES ($T_A = 25\text{ }^\circ\text{C}$ unless otherwise noted)

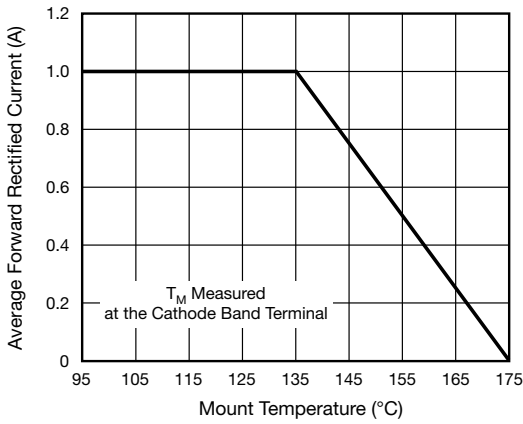


Fig. 1 - Maximum Forward Current Derating Curve

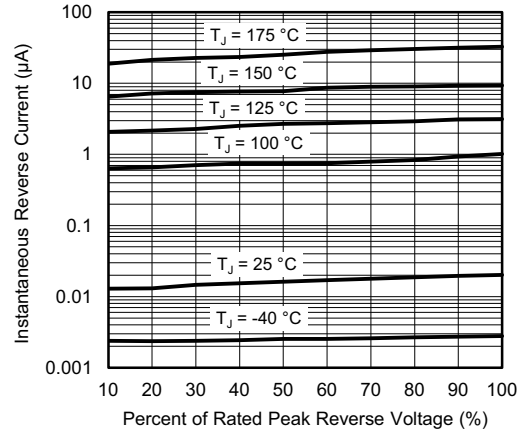


Fig. 4 - Typical Reverse Characteristics

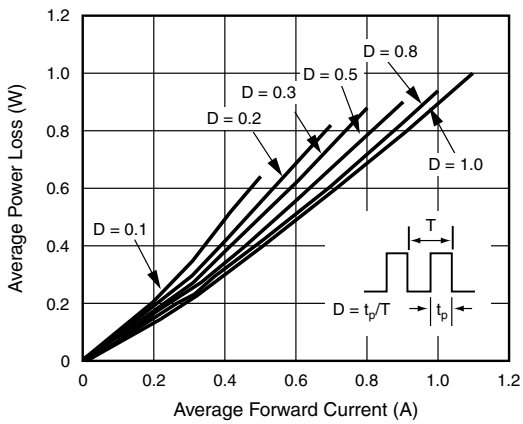


Fig. 2 - Forward Power Loss Characteristics

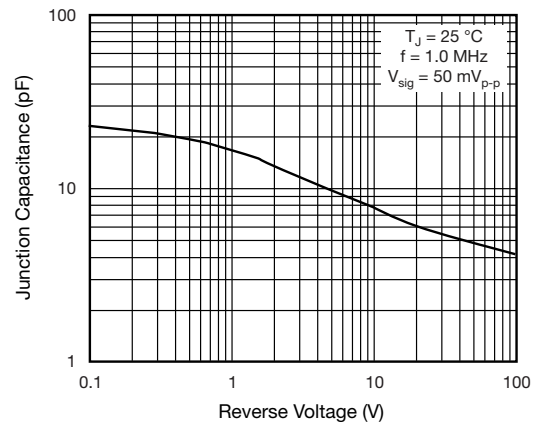


Fig. 5 - Typical Junction Capacitance

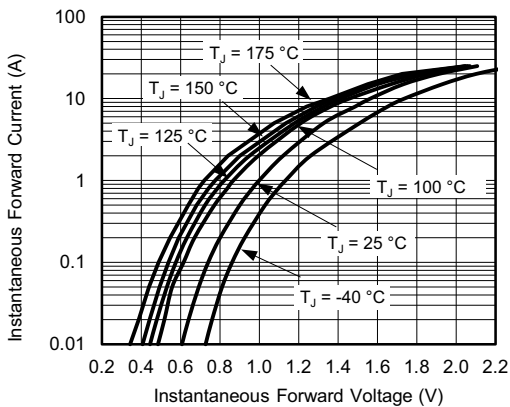


Fig. 3 - Typical Instantaneous Forward Characteristics

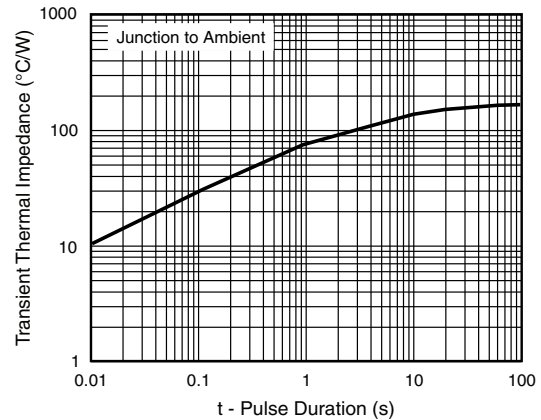
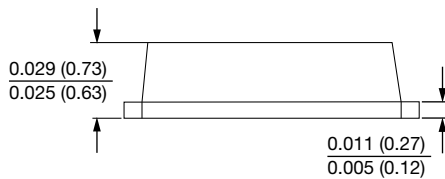
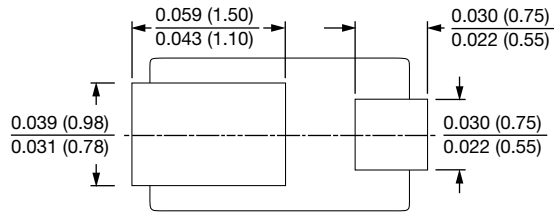
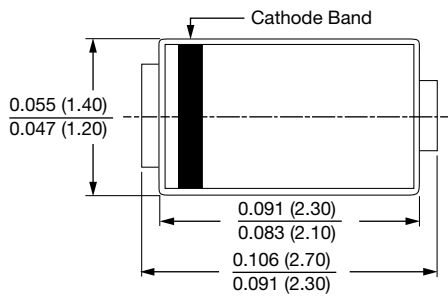


Fig. 6 - Typical Transient Thermal Impedance

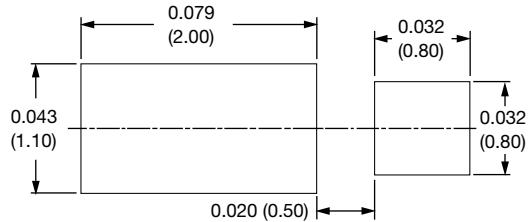


PACKAGE OUTLINE DIMENSIONS in inches (millimeters)

MicroSMP (DO-219AD)



Mounting Pad Layout





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